MA4Z713 (MA4S713)

Silicon epitaxial planar type

For switching

For wave detection

Features

- Two isolated elements are contained in one package, allowing high-density mounting
- Forward voltage V_F , optimum for low voltage rectification
- Optimum for high frequency rectification because of its short reverse recovery time (t_{rr})

■ Absolute Maximum Ratings T_a = 25°C

Parameter		Symbol	Rating	Unit
Reverse voltage		V_R	30	V
Maximum peak reverse voltage		V_{RM}	30	V
Peak forward	Single	I_{FM}	150	mA
current	Double *		110	
Forward current	Single	I_F	30	mA
	Double *		20	
Junction temperature		T _j	125	°C
Storage temperature		T_{stg}	-55 to +125	°C

Note) *: Value of each diode in double diodes used.

■ Package

Code
 SMini4-F1

• Pin Name

1: Anode 1 3: Cathode 2 2: Anode 2 4: Cathode 1

■ Marking Symbol: M1N

■ Internal Connection



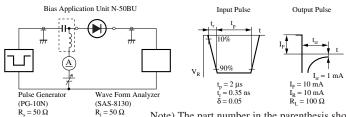
■ Electrical Characteristics $T_a = 25$ °C ± 3 °C

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Reverse current	I_R	$V_R = 30 \text{ V}$			1	μΑ
Forward voltage	V _{F1}	$I_F = 1 \text{ mA}$			0.4	V
	V _{F2}	$I_F = 30 \text{ mA}$			1.0	
Terminal capacitance	C _t	$V_R = 1 \text{ V, } f = 1 \text{ MHz}$		1.5		pF
Reverse recovery time *	t _{rr}	$I_F = I_R = 10 \text{ mA}$		1.0		ns
		$I_{rr} = 1 \text{ mA}, R_L = 100 \Omega$				
Detection efficiency	η	$V_{in} = 3 V_{(peak)}$, $f = 30 MHz$		65		%
		$R_L = 3.9 \text{ k}\Omega, C_L = 10 \text{ pF}$				

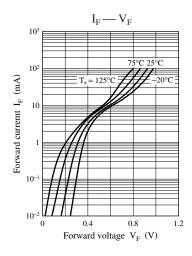
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

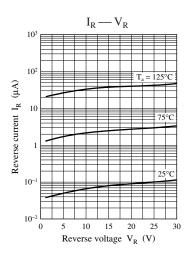
- 2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.
- 3. Absolute frequency of input and output is 2 GHz.

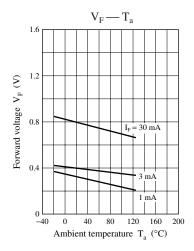
4.*: t_{rr} measurement circuit

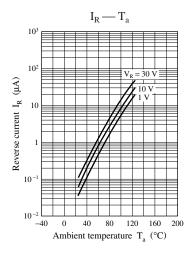


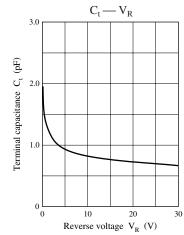
Note) The part number in the parenthesis shows conventional part number.

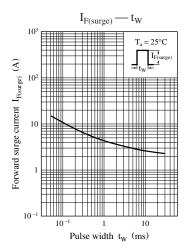












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